

What is claimed is:

1. A semiconductor component comprising a carrier board and a plurality of semiconductor chips wherein the semiconductor chips are fitted on the carrier board such that main planes thereof run perpendicular to the carrier board.
2. The semiconductor component according to claim 1, wherein the semiconductor chips are connected to the carrier board by soldered connections.
3. The semiconductor component according to claim 1, wherein the semiconductor chips have printed lines on a respective main side for electrically connecting contact points of the semiconductor chips to contact areas of the carrier board.
4. The semiconductor component according to claim 3, wherein the printed lines run beyond lower edges of the main side onto base sides of the semiconductor chips.
5. The semiconductor components according to claim 1, wherein two of the semiconductor chips are combined to form a chip composite.
6. The semiconductor component according to claim 5, wherein the two semiconductor chips are connected to one another by an adhesive at main sides free of contact points.
7. A main board for a computer system, having a semiconductor component comprising a carrier board and a plurality of semiconductor chips, wherein the carrier board of the semiconductor component is arranged parallel

to the main board.

8. A method for producing semiconductor components, comprising:

- 5       printing electrical lines of main sides of semiconductor chips such that the lines run from contact points of the semiconductor chips beyond lower edges of the main sides onto base sides of the semiconductor chips;
- 10       producing a chip composite by adhesively bonding together non-printed main sides of two semiconductor chips; and
- 15       fitting the chip composite on a carrier board such that main planes of the semiconductor chips run perpendicular to the carrier board.

9. The method according to claim 8, wherein the adhesive bonding comprises:

- 20       introducing an adhesive between the main sides of the semiconductor chips ; and
- bringing together the semiconductor chips in an adhesive bonding mold such that an at least partial encapsulation of the chip composite is produced.

- 25   10. The method according to claim 8, wherein the fitting of the chip composite comprises production of soldered connections between the printed lines and contact areas of the carrier board.